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### FDB8442

# N-Channel PowerTrench® MOSFET 40V, 80A, 2.9m $\Omega$

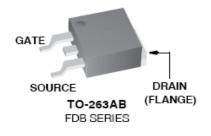
### **Features**

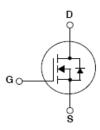
- Typ  $r_{DS(on)} = 2.1 \text{m}\Omega$  at  $V_{GS} = 10 \text{V}$ ,  $I_D = 80 \text{A}$
- Typ  $Q_{g(10)} = 181nC$  at  $V_{GS} = 10V$
- Low Miller Charge
- Low Q<sub>rr</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHs Compliant

### **Applications**

- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alernator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems







Units

### $\textbf{MOSFET Maximum Ratings} \ \, \textbf{T}_{C} = 25^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	±20	V
	Drain Current Continuous (T <sub>C</sub> <158 °C, V <sub>GS</sub> = 10V)	80	
$I_D$	Drain Current Continuous (T <sub>amb</sub> = 25°C, V <sub>GS</sub> = 10V, with R <sub>θJA</sub> = 43°C/W)	28	Α
	Pulsed	See Figure 4	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1	720	mJ
В	Power Dissipation	254	W
$P_{D}$	Derate above 25°C	1.7	W/°C
$T_J$ , $T_{STG}$	Operating and Storage Temperature	-55 to +175	°C

### **Thermal Characteristics**

F	$R_{ heta JC}$	Thermal Resistance Junction to Case	0.59	°C/W
F	$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263, lin <sup>2</sup> copper pad area	43	°C/W

### **Package Marking and Ordering Information**

De	vice Marking	Device	Package	Reel Size	Tape Width	Quantity
	FDB8442	FDB8442	TO-263AB	330mm	24mm	800 units

### **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Parameter

Off Characteristics							
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_G$	iS = 0V	40	-	-	V
J. Zara Cata V	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 32V		-	-	1	^
IDSS	Zero Gate Voltage Drain Current	$V_{GS} = 0V$	$T_J = 150$ °C	-	-	250	μΑ
less	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		_	-	±100	nA

Test Conditions

Min

Тур

Max

### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	2	2.9	4	V
		I <sub>D</sub> = 80A, V <sub>GS</sub> = 10V	-	2.1	2.9	
r <sub>DS(on)</sub>	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V,$ $T_J = 175^{\circ}C$	-	3.6	5.0	mΩ

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V,		-	12200	-	pF
C <sub>oss</sub>	Output Capacitance			-	1040	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 111112		-	640	-	pF
$R_G$	Gate Resistance	$V_{GS} = 0.5V, f = 1N$	ИHz	-	1.0	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		-	181	235	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	$V_{DD} = 20V$	-	23	30	nC
Q <sub>gs</sub>	Gate to Source Gate Charge		I <sub>D</sub> = 80A	-	49	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau		$I_g = 1mA$	-	26	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	41	-	nC

# **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switchi	ng Characteristics					
t <sub>(on)</sub>	Turn-On Time		-	-	62	ns
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 20V, I <sub>D</sub> = 80A	-	19.5	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	19.3	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 2\Omega$	-	57	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	17.2	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	118	ns

### **Drain-Source Diode Characteristics**

V	Source to Drain Diode Voltage	I <sub>SD</sub> = 80A	DA - (	0.9	1.25	V
V <sub>SD</sub>	Source to Drain blode Voltage	I <sub>SD</sub> = 40A	•	0.8	1.0	٧
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 75A, di/dt = 100A/μs	-	49	64	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 75A$ , di/dt = 100A/ $\mu$ s	-	70	91	nC

Notes: 1: Starting  $T_J = 25^{\circ}C$ , L = 0.35mH,  $I_{AS} = 64A$  2: Pulse width = 100s.

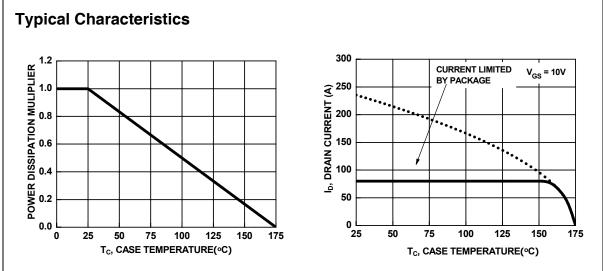


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

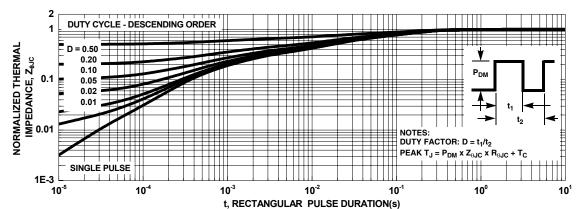


Figure 3. Normalized Maximum Transient Thermal Impedance

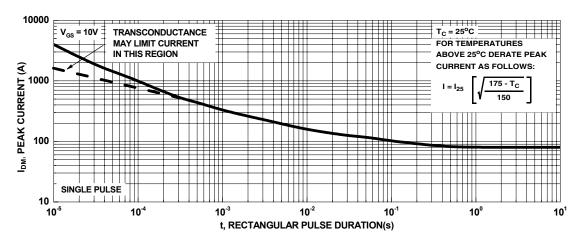


Figure 4. Peak Current Capability

### **Typical Characteristics**

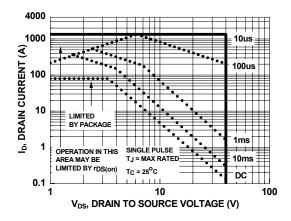
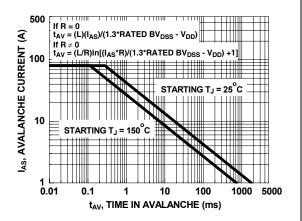
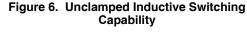


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching



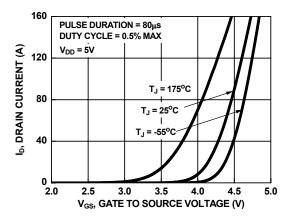


Figure 7. Transfer Characteristics

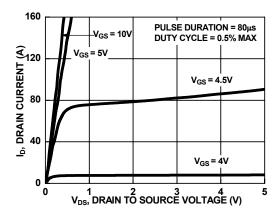


Figure 8. Saturation Characteristics

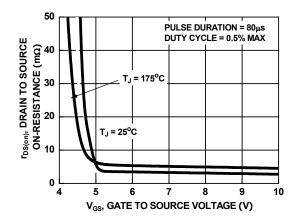


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

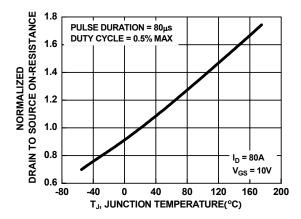


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

### **Typical Characteristics**

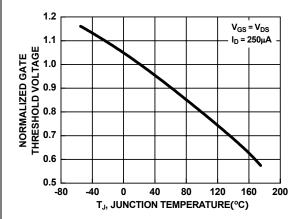


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

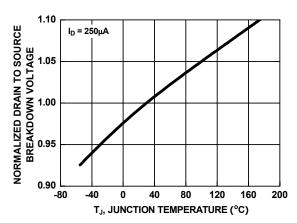


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

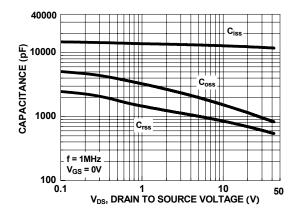


Figure 13. Capacitance vs Drain to Source Voltage

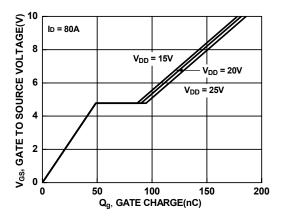


Figure 14. Gate Charge vs Gate to Source Voltage

UniFET™  $\mathsf{UltraFET}^{\circledR}$  $VCX^{\mathsf{TM}}$ Wire™

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